

#### ■ Features

• High Power: 190W(Typ.) @  $P_{IN}$ =38dBm • High Efficiency: 62%(Typ.) @  $P_{IN}$ =38dBm

· Broad Band: 2.85 to 3.3GHz

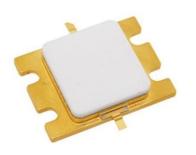
• Impedance Matched  $Z_{IN}/Z_{OUT} = 50$  ohm

Long Pulse/High Duty Capable

· Hermetically Sealed Package: IV-Package



Sumitomo Electric's GaN-HEMT SGN2833-150L-R offers high power, high efficiency and greater consistency covering 2.85 to 3.3 GHz for S-band radar applications with 50V and long pulse/high duty operation.



ABSOLUTE MAXIMUM RATING (Case Temperature  $T_c$ =25 deg.C)

Item	Symbol	Rating	Unit
Operating Voltage	$V_{DS}$	55	V
Drain-Source Voltage	$V_{DS}$	250 @ V <sub>GS</sub> -10V	V
Gate-Source Voltage	$V_{GS}$	-15	V
Storage Temperature	T <sub>stg</sub>	-55 to +125	deg.C
Channel Temperature	T <sub>ch</sub>	+250	deg.C

#### RECOMMENDED OPERATING CONDITION

Item	Symbol	Condition	Limit	Unit
Drain-Source Voltage	$V_{DS}$		<=50	V
Forward Gate Current	$I_{GF}$	Rg=12ohm	<=76	mA
Reverse Gate Current	$\mathbf{I}_{GR}$	Rg=12ohm	>=-5.2	mA
Peak Channel Temperature	T <sub>ch-peak</sub>		<=200	deg.C
Output Power	P <sub>out</sub>		<=P <sub>5dB</sub>	dBm

#### ELECTRICAL CHARACTERISTICS (Case Temperature $T_c=25 \text{ deg.C}$ )

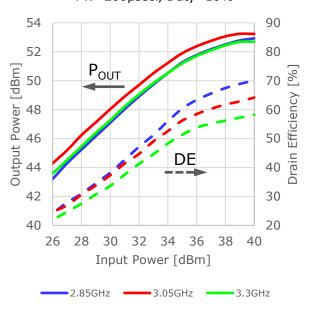
Item	Symbol	Condition	Limit			Unit
Item		Condition	Min.	Тур.	Max.	Onit
Pinch-off Voltage	$V_P$	$V_{DS}$ =50V, $I_{DS}$ =28mA	-3.45	-3.00	-2.45	V
Frequency Range	Freq.	$V_{DS}$ =50V-typ. $I_{DS(DC)}$ =0.5A-typ. Pulse Width=200 $\mu$ sec. Duty=10% $P_{in}$ =38dBm	2.85	-	3.3	GHz
Output Power	P <sub>out</sub>		51.8	52.8	-	dBm
Drain Efficiency	DE		-	62.0	-	%
Power Gain	$G_P$		13.8	14.8	-	dB
Gain Flatness	GF		-	0.7	1.5	dB
Load Mismatch Ruggedness	VSWR		-	10:1	=	-
Thermal Resistance	R <sub>th</sub>	Channel to Case at 45W P <sub>DC</sub>	-	1.1	1.3	deg.C/W

CASE STYLE	IV	
RoHS Compliance	YES	

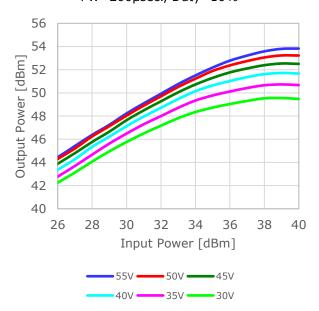


#### ■ RF Characteristics

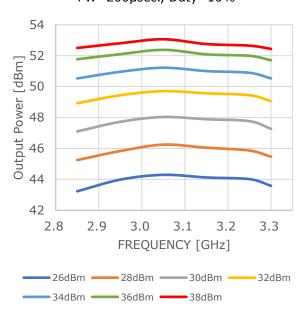
# Output Power & Drain Efficiency vs. Input Power $V_{DS}=50V$ , $I_{DS(DC)}=0.5A$ $PW=200\mu sec.$ , Duty=10%



## Output Power vs. Input Power by Drain Voltage f=3.05GHz, I<sub>DS(DC)</sub>=0.5A PW=200µsec., Duty=10%

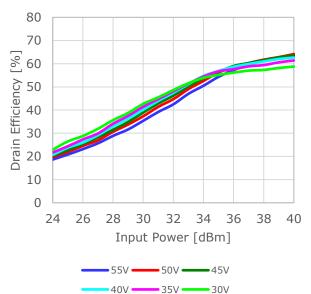


#### Output Power vs. Frequency by Input Power V<sub>DS</sub>=50V, I<sub>DS(DC)</sub>=0.5A PW=200µsec., Duty=10%



# Drain Efficiency vs. Input Power by Drain Voltage

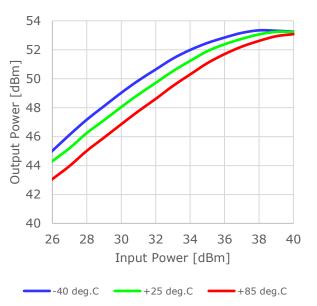
Freq.=3.05GHz,  $I_{DS(DC)}$ =0.5A PW= $200\mu$ sec., Duty=10%



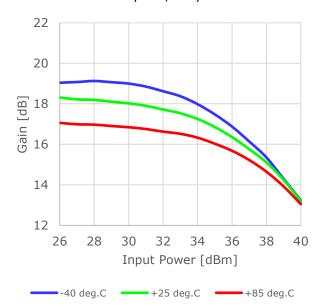


#### ■ RF Characteristics

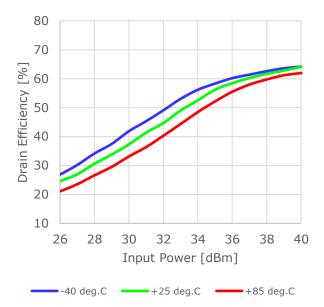
Output Power vs. Input Power by case temperature Freq.=3.05GHz,  $V_{DS}$ =50V,  $I_{DS(DC)}$ =0.5A PW=200 $\mu$ sec., Duty=10%



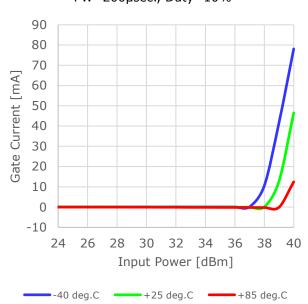
Gain vs. Input Power by case temperature Freq.=3.05GHz,  $V_{DS}$ =50V,  $I_{DS(DC)}$ =0.5A PW=200 $\mu$ sec., Duty=10%



Output Power vs. Input Power by case temperature Freq.=3.05GHz,  $V_{DS}$ =50V,  $I_{DS(DC)}$ =0.5A PW=200 $\mu$ sec., Duty=10%



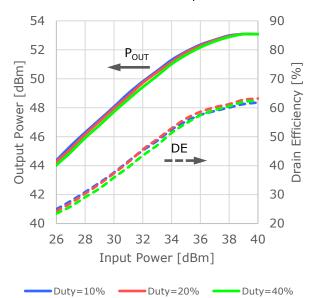
Gate Current vs. Input Power by case temperature Freq.=3.05GHz,  $V_{DS}$ =50V,  $I_{DS(DC)}$ =0.5A PW=200 $\mu$ sec., Duty=10%



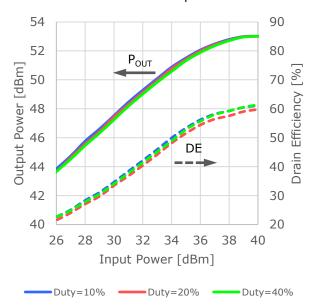


#### ■ RF Characteristics

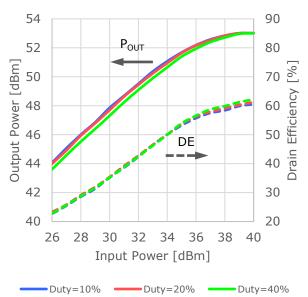
Output Power, Drain Efficiency vs. Input Power by Duty cycle Freq.=3.05GHz, V<sub>DS</sub>=50V, I<sub>DS(DC)</sub>=0.5A Pulse width=200µsec.



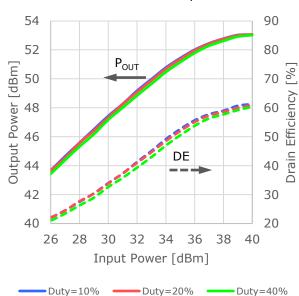
Output Power, Drain Efficiency vs. Input Power by Duty cycle Freq.=3.05GHz, V<sub>DS</sub>=50V, I<sub>DS(DC)</sub>=0.5A Pulse width=1000µsec.



Output Power, Drain Efficiency vs. Input Power by Duty cycle Freq.=3.05GHz,  $V_{DS}$ =50V,  $I_{DS(DC)}$ =0.5A Pulse width=500 $\mu$ sec.

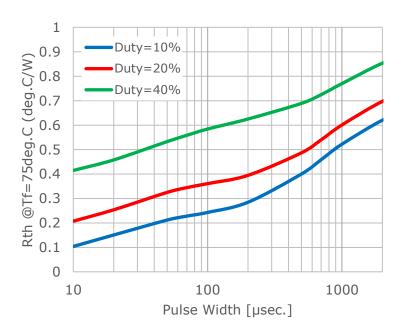


Output Power, Drain Efficiency vs. Input Power by Duty cycle Freq.=3.05GHz,  $V_{DS}$ =50V,  $I_{DS(DC)}$ =0.5A Pulse width=2000 $\mu$ sec.





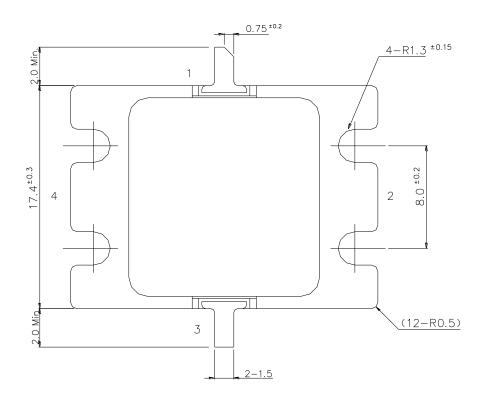
# ■ Thermal Characteristics In Pulsed Operation

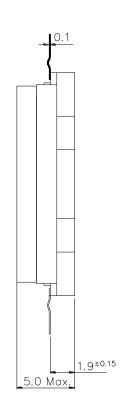


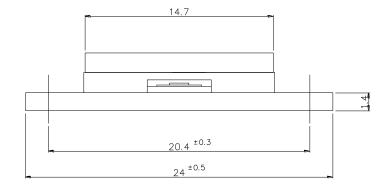


# ■ Package Outline

Case Style: IV







1:Gate

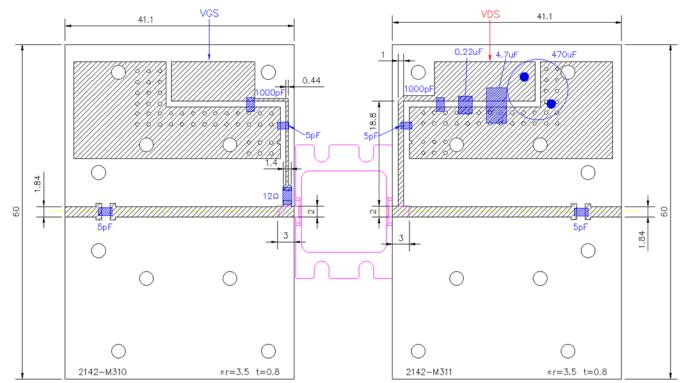
2:Source(Flange)

3: Drain

4:Source(Flange)

Unit : mm

## ■ Test Fixture



PCB: h=0.8mm,  $\epsilon r=3.5$ , Cu=18um

Unit: mm



#### For Safety, Observe the Following Procedures Environmental Management

- Do not put this product into the mouth.
- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.
- Respect all applicable laws of the country when discarding this product.
  This product must be disposed in accordance with methods specified by applicable hazardous waste procedures.

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